Special Issue

Structural Health Monitoring Based on Deep Learning and Image Processing

Message from the Guest Editors

Structural health monitoring (SHM) is a vital technology for ensuring the safety, functionality, and longevity of critical components and systems across a wide spectrum of engineering domains. With recent advances in artificial intelligence, particularly deep learning and image processing, SHM has entered a new era of intelligent, data-driven assessment capable of detecting subtle defects and predicting failures in real time. This Special Issue aims to present cutting-edge research on SHM methods that integrate deep learning algorithms and image-based techniques across diverse engineering disciplines. Topics of interest include, but are not limited to, the following:

- Image- and video-based defect detection (e.g., cracks, corrosion, and delamination);
- Deep learning for damage localization, classification, and prognosis;
- Computer vision and 3D reconstruction for surface and volumetric monitoring;
- Multi-modal sensor fusion combining visual, acoustic, and vibration data;
- UAV and robotic visual inspection systems powered by AI;
- Transfer learning, domain adaptation, and lightweight models for real-time SHM;
- Case studies and field applications in complex operational environments.

Guest Editors

Dr. Ziqian Yang

School of Mechanical and Aerospace Engineering, Nanyang Technological University, Singapore 639798, Singapore

Dr. Qingsong Xiong

Department of Civil and Environmental Engineering, The Hong Kong Polytechnic University, Hong Kong 999077, China

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Electronics is a multidisciplinary journal designed to appeal to a diverse audience of research scientists, practitioners, and developers in academia and industry. The journal is devoted to fast publication of latest technological breakthroughs, cutting-edge developments, and timely reviews of current and emerging technologies related to the broad field of electronics. Experimental and theoretical results are published as regular peer-reviewed articles or as articles within Special Issues guestedited by leading experts in selected topics of interest.

Editor-in-Chief

Prof. Dr. Flavio Canavero
Department of Electronics and Telecommunications, Politecnico di Torino, 10129 Torino, Italy

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